

IN THE SPECIFICATION

Please amend the specification as follows:

At page 5, line 17, following the word symbol "θ", second occurrence, please insert the numeral --115--.

IN THE CLAIMS

Please delete nonelected claims 6-17.

Please amend the following claims:

1. (Amended) ^{Electroplating} A method of applying a liquid material onto a substrate surface, comprising[the steps of]:

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placing a[the] substrate surface within an enclosure;
coupling an anode to the substrate surface, coupling an anode to the cathode
introducing a[the] liquid material into the enclosure; and
the cathode is 20-60 degrees from vertical
directing the liquid material angularly toward the substrate surface so that the liquid

a
material flows rotationally upon contact with the substrate surface.

2. (Amended) A method of applying a liquid material as in claim 1, further comprising[the steps of]:

pressing the substrate against the enclosure to form a seal.

3. (Amended) A method of applying a liquid material as in claim 1, further comprising[the steps of]:

providing a cathode contact;

coupling the cathode contact to the substrate surface;

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providing an anode coupled to the cathode; and

wherein the liquid material is an electrolytic bath to form an electrochemical cell.

4. (Amended) A method of applying a liquid material as in claim 3, further comprising[the step of]:

forming a metallic film on the substrate surface.

18. (Amended) A method of electroplating a material onto a substrate surface within an enclosed chamber, comprising[the steps of]:

securing a[the] substrate within an opening in a[the] chamber so that the substrate surface faces the chamber interior;

coupling a cathode to the substrate surface;

coupling an anode to the cathode; and

introducing a liquid electrochemical bath to the chamber interior and directing the liquid angularly *at approximately 20 to 60 degrees from vertical* toward the substrate surface so that the liquid flows rotationally upon contact with the substrate surface.

19. (Amended) A method of electroplating a material as in claim 18, wherein[the step of] introducing a liquid further includes spraying the liquid out of a plurality of spray outlets.

Sub B3
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21. (Amended) A method of electroplating a material as in claim 19[20], wherein the spray outlets are angled at approximately 20 to 60 degrees from vertical.

Please add the following new claims.

Sub B4
27. (New) A method of applying a liquid material onto a substrate surface as in claim 1, wherein introducing the liquid further includes spraying the liquid out of a plurality of spray outlets.

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28. (New) A method of applying a liquid material onto a substrate surface as in claim 27, wherein the spray outlets are angled at approximately 20 to 60 degrees from vertical.

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29. (New) A method of applying a liquid material onto a substrate surface as in claim 1, wherein the liquid is directed radially outward with respect to the center of the substrate surface.

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30. (New) A method of applying a liquid material onto a substrate surface as in claim 1, wherein the liquid is directed circumferentially with respect to a perpendicular direction toward the substrate surface.

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Sub B4
31. (New) A method of applying a liquid material onto a substrate surface as in claim 27, wherein at least one of the plurality of spray outlets is pointed in a perpendicular direction toward the center of the substrate surface.

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32. (New) A method of applying a liquid material onto a substrate surface as in claim 27, wherein the plurality of spray outlets includes at least four spray outlets forming a cross pattern.

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33. (New) A method of applying a liquid material onto a substrate surface as in claim 27, wherein the plurality of spray outlets further includes at least one spray outlet located at the center of the cross pattern.

34. (New) A method of applying a liquid material onto a substrate surface, comprising:

? → placing a semiconductor substrate surface within an enclosure;
coupling a cathode to the semiconductor substrate;
coupling an anode to the cathode;
providing a nozzle having a plurality of spray outlets, wherein the spray

outlets are angled at approximately 20 to 60 degrees from vertical;

introducing a liquid material into the nozzle; and

directing the liquid material through the plurality of spray outlets toward the substrate surface so that the liquid material flows rotationally upon contact with the substrate surface.

35. (New) A method of applying a liquid material onto a substrate surface according to claim 34, wherein the liquid is directed circumferentially with respect to a perpendicular direction toward the substrate surface.

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36. (New) A method of applying a liquid material onto a substrate surface according to claim 34, wherein at least one of the plurality of spray outlets is pointed in a perpendicular direction toward the center of the substrate surface.

37. (New) A method of applying a liquid material onto a substrate surface according to claim 34, wherein the plurality of spray outlets includes at least four spray outlets forming a cross pattern.

38. (New) A method of applying a liquid material onto a substrate surface according to claim 37, wherein the plurality of spray outlets further includes at least one spray outlet located at the center of the cross pattern.

REMARKS

The specification was amended to correct a typographical error.

Claims 1-26 were pending. Nonelected claims 6-17 and claim 20 were deleted.

New claims 27-38 were added. All of the limitations of new claims 27-38 were previously examined, and therefore no further search is needed. No new matter was introduced by amendment of the claims.